



Sheet 1 of 2

FORM PTO-1449 (REV. 7-80)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. H-987		SERIAL NO. 09/869,274	
LIST OF DOCUMENTS CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT A. NISHIMURA et al			
				FILING DATE June 26, 2001		GROUP	
U.S. PATENT DOCUMENTS							
* EXAMINER INITIAL		DOCUMENT	DATE	NAME	CLASS	SUBCLASS	FILING DATE (If Appropriate)
	AA	6,030,890	2/29/00	Iwabuchi			
	AB	6,008,543	12/28/99	Iwabuchi			
	AC	5,554,940	9/10/96	Hubacher			
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
FOREIGN PATENT DOCUMENTS							
		DOCUMENT	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
	AL	4-26537	3/3/92	Japan			<input type="checkbox"/> <input checked="" type="checkbox"/>
	AM	4-96343	3/27/92	Japan			<input type="checkbox"/> <input checked="" type="checkbox"/>
	AN	5-218042	8/27/93	Japan			<input checked="" type="checkbox"/> <input type="checkbox"/>
	AO	8-250498	9/27/96	Japan			<input type="checkbox"/> <input checked="" type="checkbox"/>
	AP	8-64633	3/8/96	Japan			<input type="checkbox"/> <input type="checkbox"/>
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)							
	AR	IEEE/CPMT INTL ELECTRONICS MANUFACTURING TECHNOLOGY SYMPOSIUM, "Impact of Wafer Probe Damage on Flip Chip Yields and Reliability", M. Varnau et al, pp. 293-297.					
	AS						
	AT						
EXAMINER 				DATE CONSIDERED 3/23/04			

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